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CONFIRMATION NO. 1133

<b>SERIAL NUMBER</b> 10/626,524	<b>FILING OR 371(c) DATE</b> 07/25/2003 <b>RULE</b>	<b>CLASS</b> 451	<b>GROUP ART UNIT</b> 3723	<b>ATTORNEY DOCKET NO.</b> ROH-0031/DIV
<b>APPLICANTS</b> Junichi Hikita, Kyoto, JAPAN; Ikuo Yoshida, Kyoto, JAPAN; Kazuhide Ino, Kyoto, JAPAN;				
<b>** CONTINUING DATA *****</b> This application is a DIV of 09/704,563 11/03/2000 PAT 6,635,512 <i>Yes RR</i>				
<b>** FOREIGN APPLICATIONS *****</b> JAPAN 11-314086 11/04/1999 JAPAN 11-314087 11/04/1999 JAPAN 11-314088 11/04/1999 <i>Yes RR</i>				
<b>IF REQUIRED, FOREIGN FILING LICENSE GRANTED</b> <b>** 04/21/2006</b>				
Foreign Priority claimed <input checked="" type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 (a-d) conditions <input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after allowance Verified and Acknowledged <i>[Signature]</i> Examiner's Signature Initials <i>RR</i>		<b>STATE OR COUNTRY</b> JAPAN	<b>SHEETS DRAWING</b> 8	<b>TOTAL CLAIMS</b> 12
<b>INDEPENDENT CLAIMS</b> 1				
<b>ADDRESS</b> Mr. Steven M. Rabin c/o Rabin & Berdo, P.C. 1101 14th Street, NW Suite 500 Washington, DC20005				
<b>TITLE</b> Method of producing a semiconductor device by dividing a semiconductor wafer into separate pieces of semiconductor chips				
<b>FILING FEE RECEIVED</b> 750	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:		<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees ( Filing ) <input type="checkbox"/> 1.17 Fees ( Processing Ext. of time ) <input type="checkbox"/> 1.18 Fees ( Issue ) <input type="checkbox"/> Other _____ <input type="checkbox"/> Credit	